

Silicon Carbide Power Schottky Barrier Diode



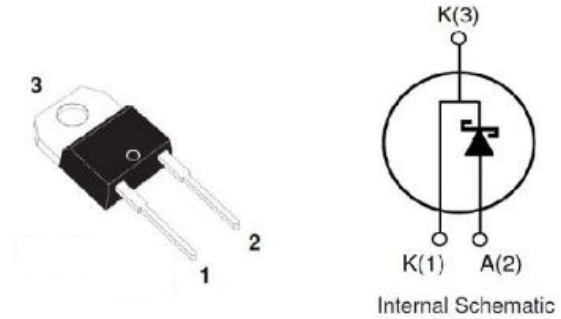
Applications:

- Power factor correction
- Solar wind inverters
- Industrial motor drivers
- Charge block for electrical cars
- Electrical household appliances
- Uninterruptible Power System(UPS)

| | | |
|-----------------------------------|-------|-----------|
| $I_F, T_c \leq 135^\circ\text{C}$ | Q_c | V_{RRM} |
| 14A | 25 nC | 600V |

Features:

- Rated to 600V at 10 Amps
- Zero reverse recovery current
- Zero forward recovery voltage
- Temperature independent switching behaviour
- High temperature operation
- High frequency operation
- Substantially reduced switching losses
- No thermal run-away with parallel devices
- Reduced heat sink requirements



Ordering Information

| Part Number | Package | Marking |
|-------------|----------|-----------|
| RSS10060A | TO-220-2 | RSS10060A |

Maximun Ratings

| Symbol | Parameter | Value | Units | Test Conditions |
|--------------------|---|------------|--------------|---|
| VRRM | Repetitive Peak Reverse Voltage | 600 | V | Tj=25°C |
| VRSM | Surge Peak Reverse Voltage | 600 | V | Tj=25°C |
| VDC | DC Blocking Voltage | 600 | V | Tj=25°C |
| IF | Continuous Forward Current | 29 | A | Tj=25°C |
| | | 14 | | Tj=135°C |
| | | 10 | | Tj=150°C |
| IFRM | Repetitive Peak Forward Surge Current | 50 | A | Tc=25°C, Tp=10mS, Half Sine Wave, D=0.3 |
| IFSM | Non-repetitive Peak Forward Surge Current | 70 | A | Tc=25°C, Tp=10mS, Half Sine Wave |
| PTOT | Power Dissipation | 53 | W | Tc=25°C |
| | | 24 | | Tc=110°C |
| Tc | Tc | 135 | °C | |
| Tj | Maximum Case Temperature | -55 to 175 | °C | |
| Tstg | Operating Junction | -55 to 175 | °C | |
| TL TPKG | Maximum Temperature for Soldering | 300 260 | °C | |
| | Leads at 0.063in(1.6mm)from Case for 10 seconds | | | |
| | Package Body for 10 seconds | | | |
| Mounting Torque | | 1 | Nm lbf-in | M3 Screw 6-32 Screw |
| | | 8.8 | | |

Thermal Resistance

| Symbol | Parameter | Value | Units | Test Conditions |
|--------|------------------|-------|-------|-----------------|
| Rth JC | Junction-to-Case | 1.29 | °C/W | |

Electrical Characteristics

| Symbol | Parameter | Typ. | Max. | Units | Test Conditions |
|--------|-------------------|------|------|-------|---|
| VF | Forward Voltage | 1.5 | 1.8 | V | IF=10A Tj=25°C |
| | | 1.9 | 2.5 | | IF=10A Tj=175°C |
| IR | Reverse Current | 10 | 100 | µA | VR=600V Tj=25°C |
| | | 15 | 200 | | VR=600V Tj=175°C |
| Qc | Total Capacitive | 25 | --- | nC | VR=600V, IF=10A, di/dt=500A/us, Tj=25°C |
| C | Total Capacitance | 600 | 700 | pF | VR=0V, Tj=25°C, f=1MHZ |
| | | 59 | 62 | | VR=200V, Tj=25°C, f=1MHZ |
| | | 58 | 60 | | VR=400V, Tj=25°C, f=1MHZ |

Performance Graphs

Figure1. Forward IV characteristics as a function of Tj

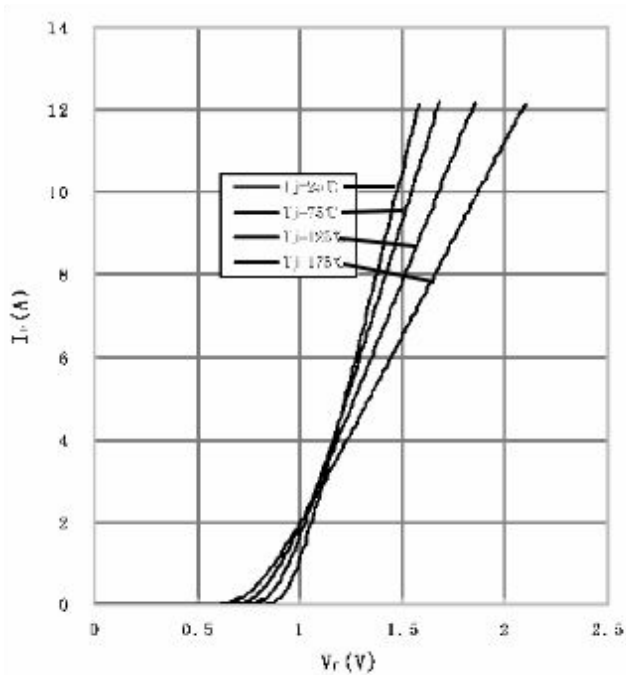
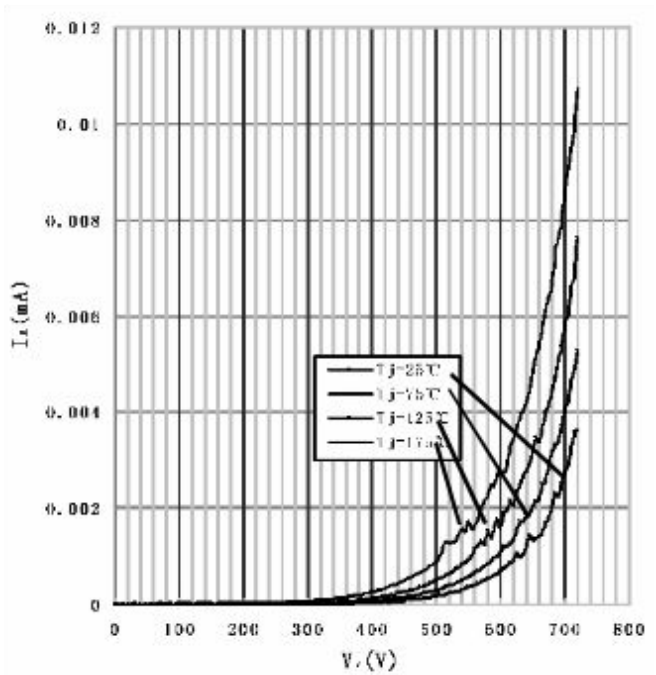


Figure2. Reverse IV characteristics as a function of Tj



Performance Graphs

Figure3. Current Derating

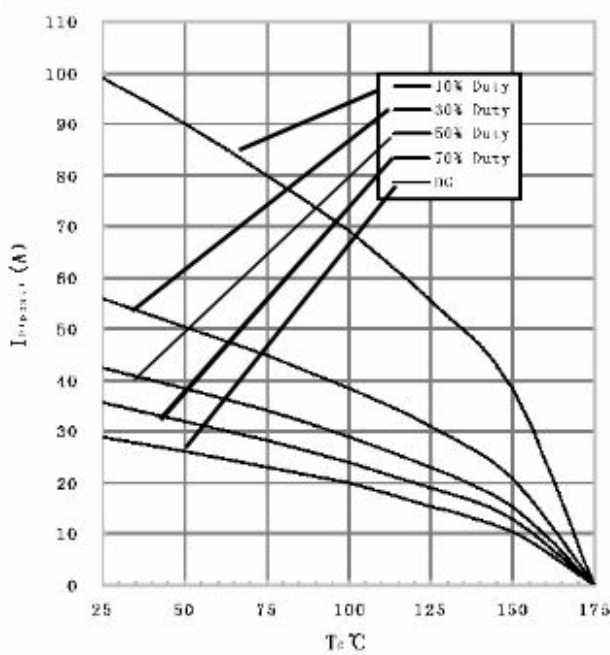
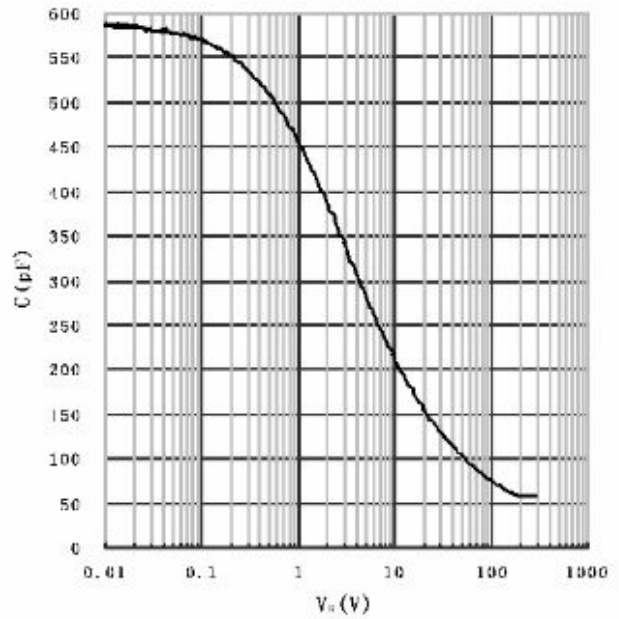
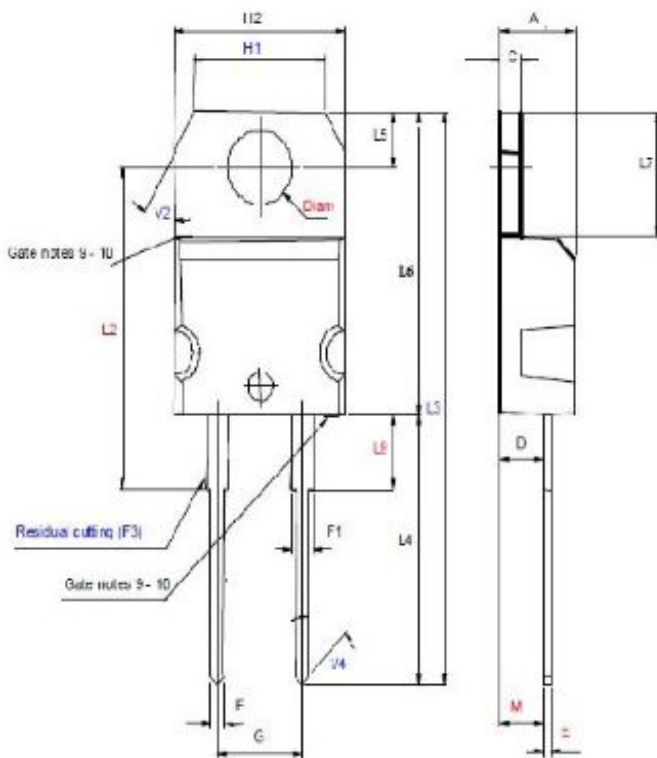


Figure4. Capacitance vs. reverse voltage



Package T0-220-2



| DIM | Millimeters | | Inches | |
|------|-------------|-------|--------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.4 | 4.6 | 0.173 | 0.181 |
| C | 1.23 | 1.32 | 0.048 | 0.052 |
| D | 2.4 | 2.72 | 0.094 | 0.107 |
| E | 0.49 | 0.7 | 0.019 | 0.028 |
| F | 0.61 | 0.88 | 0.024 | 0.035 |
| F1 | 1.14 | 1.7 | 0.045 | 0.067 |
| F3 | | 1 | | 0.039 |
| G | 4.95 | 5.15 | 0.195 | 0.203 |
| H1 | 7.7 | 7.9 | 0.303 | 0.311 |
| H2 | 10 | 10.4 | 0.394 | 0.409 |
| L2 | 16.4 | | 0.646 | |
| L3 | 28.9 | | 1.138 | |
| L4 | 13 | 14 | 0.512 | 0.551 |
| L5 | 2.65 | 2.95 | 0.104 | 0.116 |
| L6 | 15.25 | 15.75 | 0.600 | 0.620 |
| L7 | 6.2 | 6.6 | 0.244 | 0.260 |
| L9 | 3.5 | 3.93 | 0.138 | 0.155 |
| M | 2.6 | | | |
| V | 5° | | | |
| V2 | 30° | | | |
| V4 | 45° | | | |
| diam | 3.75 | 3.85 | 0.148 | 0.152 |

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